

CM1242-33CP

1-Channel ESD Protection Device in 0201 CSP

Description

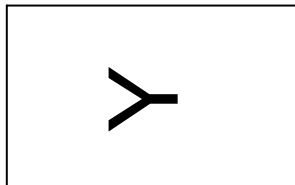
The CM1242-33CP is a 2-bump ESD protection device in 0201 CSP form factor. It is fully compliant with IEC 61000-4-2. The CM1242-33CP is also RoHS II compliant and has a pure tin finish.

Table 1. PIN DESCRIPTIONS

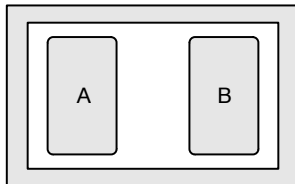
Pin	Description
A	ESD Channel Pin 1
B	ESD Channel Pin 2

PACKAGE / PINOUT DIAGRAMS

Top View
(Bumps Down)



Bottom View
(Bumps Up)



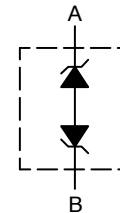
ON Semiconductor®

<http://onsemi.com>

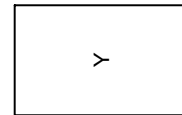


WLCSP2
CP SUFFIX
CASE 567AV

BLOCK DIAGRAM



MARKING DIAGRAM



Y = Specific Device Code

ORDERING INFORMATION

Device	Package	Shipping
CM1242-33CP	CSP (Pb-Free)	10,000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

CM1242-33CP

SPECIFICATIONS

Table 2. STANDARD OPERATING CONDITIONS

Parameter	Rating	Units
Storage Temperature Range	-55 to +150	°C
Operating Temperature Range	-40 to +85	°C
Maximum Input Voltage	±5.5	V

Table 3. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V_B	Breakdown Voltage	$I_F = +10 \text{ mA}$ $I_F = -10 \text{ mA}$	6.0 -9.0	7.6 -7.6	9.0 -6.0	V
I_{LEAK}	Channel Leakage Current	$V_{IN} = \pm 3.3 \text{ V}$		±0.1	±0.5	μA
C_{IN}	Channel Input Capacitance	At 1 MHz, $V_{IN} = 0 \text{ V}$	45	55	66	pF
V_{ESD}	ESD Protection Peak Discharge Voltage at any channel input a) Contact Discharge per IEC 61000-4-2 standard b) Air Discharge per IEC 61000-4-2 standard	(Note 2)	±30 ±30			kV
V_{CL}	Channel Clamp Voltage Positive Transients Negative Transients	$I_{PP} = 1 \text{ A}$, $t_p = 8/20 \text{ μs}$		+8.6 -8.6		V
R_{DYN}	Dynamic Resistance Positive Transients Negative Transients	$I_{PP} = 1 \text{ A}$, $t_p = 8/20 \text{ μs}$		0.4 0.4		Ω

- $T_A = 25^\circ\text{C}$ unless otherwise specified.
- Standard IEC 61000-4-2 with $C_{Discharge} = 150 \text{ pF}$, $R_{Discharge} = 330 \text{ Ω}$.

CM1242-33CP

MECHANICAL SPECIFICATIONS

CM1242-33CP Mechanical Specifications

The CM1242-33CP is supplied in a 2-bump Chip Scale Package (CSP). Dimensions are presented below.

Table 4. CSP TAPE AND REEL SPECIFICATIONS

Part Number	Chip Size (mm)	Pocket Size (mm) $B_0 \times A_0 \times K_0$	Tape Width W	Reel Diameter	Qty per Reel	P_0	P_1
CM1242-33CP	0.60 X 0.30 X 0.275	0.67 X 0.37 X 0.35	8 mm	178 mm (7")	10,000	4 mm	2 mm

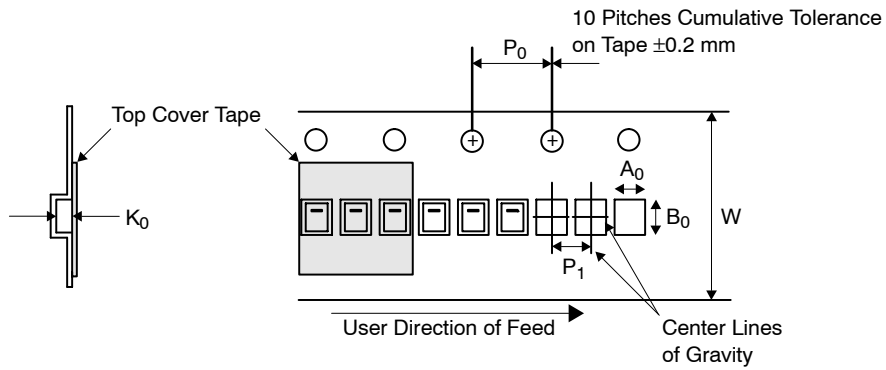


Figure 1. Tape and Reel Mechanical Data

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

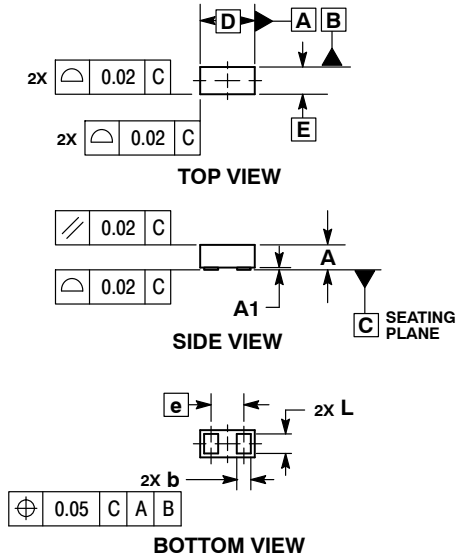
ON Semiconductor®



SCALE 12:1

WLCSP2, 0.6x0.3
CASE 567AV
ISSUE C

DATE 22 SEP 2017



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.250	0.275	0.300
A1	0.000	0.025	0.050
b	0.140	0.155	0.170
D	0.570	0.600	0.630
E	0.270	0.300	0.330
e	0.36 BSC		
L	0.190	0.215	0.240

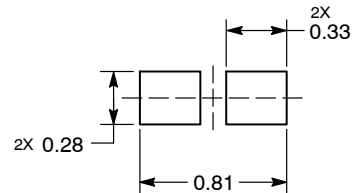
GENERIC MARKING DIAGRAM*



X = Specific Device Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED SOLDER FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON49805E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	WLCSP2, 0.6X0.3	PAGE 1 OF 1

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT

North American Technical Support:

Voice Mail: 1 800-282-9855 Toll Free USA/Canada

Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative

